

# 20 V, 4.0 A, Low V<sub>CE(sat)</sub> **PNP Transistor**

# **NSS20200LT1G**, **NSV20200LT1G**

onsemi's e<sup>2</sup>PowerEdge family of low V<sub>CE(sat)</sub> transistors are miniature surface mount devices featuring ultra low saturation voltage (V<sub>CE(sat)</sub>) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

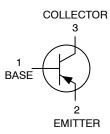
#### **Features**

- AEC-Q101 Qualified and PPAP Capable
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

# -20 VOLTS **4.0 AMPS** PNP LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 65 m $\Omega$



SOT-23 (TO-236) **CASE 318** STYLE 6



#### MARKING DIAGRAM



VC = Specific Device Code

= Date Code\* = Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS20200LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSV20200LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-20	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-20	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-7.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	-2.0	Α
Collector Current - Peak	I <sub>CM</sub>	-4.0	Α
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 1)	460 3.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	270	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	540 4.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	230	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 @ 100 mm², 1 oz. copper traces.

2. FR-4 @ 500 mm², 1 oz. copper traces.

<sup>3.</sup> Thermal response.

### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•		•
Collector – Emitter Breakdown Voltage $(I_C = -10 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	-20	-	-	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-20	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	-7.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -20 Vdc, I <sub>E</sub> = 0)	Ісво	_	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -7.0 Vdc)	I <sub>EBO</sub>	_	-	-0.1	μAdc
ON CHARACTERISTICS			•		•
DC Current Gain (Note 4) $ \begin{array}{l} (I_C = -10 \text{ mA, V}_{CE} = -2.0 \text{ V}) \\ (I_C = -500 \text{ mA, V}_{CE} = -2.0 \text{ V}) \\ (I_C = -500 \text{ mA, V}_{CE} = -2.0 \text{ V}) \\ (I_C = -1.0 \text{ A, V}_{CE} = -2.0 \text{ V}) \\ (I_C = -2.0 \text{ A, V}_{CE} = -2.0 \text{ V}) \end{array} $	h <sub>FE</sub>	250 250 180 150	- 300 - -	- - - -	
Collector – Emitter Saturation Voltage (Note 4) $ \begin{pmatrix} I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A} \end{pmatrix} \text{ (Note 5)} \\ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A} \end{pmatrix} \\ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.010 \text{ A} \end{pmatrix} \\ \begin{pmatrix} I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A} \end{pmatrix} $	V <sub>CE(sat)</sub>	- - -	-0.008 -0.065 -0.100 -0.130	-0.013 -0.090 -0.120 -0.180	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.01 \text{ A})$	V <sub>BE(sat)</sub>	-	-	-0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	_	-	-0.900	V
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	-	-	MHz
Input Capacitance (V <sub>EB</sub> = 0.5 V, f = 1.0 MHz)	Cibo	-	-	330	pF
Output Capacitance (V <sub>CB</sub> = 3.0 V, f = 1.0 MHz)	Cobo	-	_	100	pF
SWITCHING CHARACTERISTICS					
Delay ( $V_{CC} = -15 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>d</sub>	-	_	60	ns
Rise (V <sub>CC</sub> = -15 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>r</sub>	1		120	ns
Storage ( $V_{CC} = -15 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>s</sub>	-	_	300	ns
Fall (V <sub>CC</sub> = -15 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>f</sub>	-	-	130	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

5. Guaranteed by design but not tested.

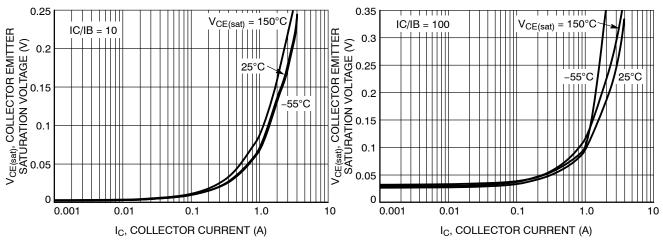


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

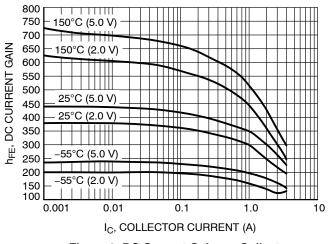


Figure 3. DC Current Gain vs. Collector Current

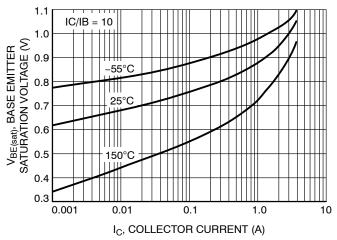


Figure 4. Base Emitter Saturation Voltage vs. Collector Current

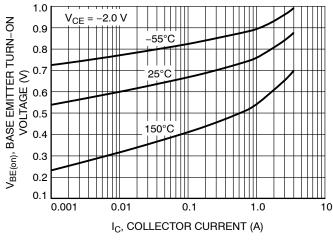


Figure 5. Base Emitter Turn-On Voltage vs.
Collector Current

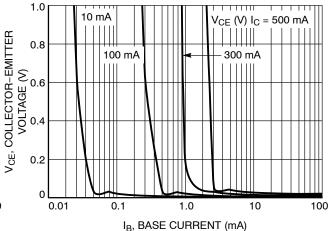
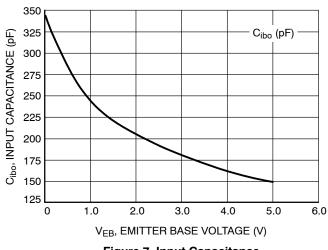


Figure 6. Saturation Region



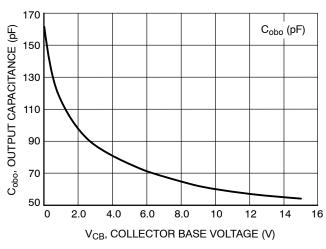


Figure 7. Input Capacitance

Figure 8. Output Capacitance

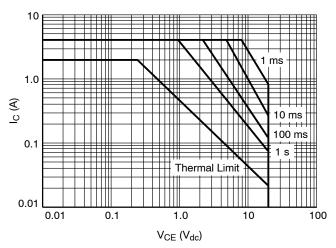


Figure 9. Safe Operating Area

**MILLIMETERS** 

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

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#### SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

**DATE 14 AUG 2024** 

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°

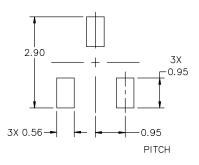




DETAIL "A" Scale 3:1







#### NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

#### RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **STYLES ON PAGE 2**

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<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR			
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	2. CATHODE 2.	2: STYLE 13: CATHODE PIN 1. SOURCE CATHODE 2. DRAIN ANODE 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	2. ANODE 2.	3: STYLE 19: NO CONNECTION PIN 1. CATHODE CATHODE 2. ANODE ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT			STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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